

Title (en)  
COMPONENT

Title (de)  
BAUELEMENT

Title (fr)  
COMPOSANT

Publication  
**EP 1500142 A2 20050126 (DE)**

Application  
**EP 03714696 A 20030312**

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• DE 0300787 W 20030312  
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Abstract (en)  
[origin: WO03094234A2] The invention relates to a component, particularly a semiconductor component, comprising a first chip (10), which is placed on a second chip (20). The main surfaces (13, 23) of the first and second chips (10, 20) are respectively provided with first and second metallizations (12, 22) that face one another. First areas of the metallizations (12, 22) are provided for establishing an electrical connection between the first and second chip (10, 20). According to the invention, second areas of the metallizations (12, 22) are provided in the form of an additional electrical functional layer located outside of the first and second chips (10, 20).

IPC 1-7  
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IPC 8 full level  
**H01L 21/60** (2006.01); **H01L 23/522** (2006.01); **H01L 23/528** (2006.01); **H01L 23/544** (2006.01); **H01L 23/552** (2006.01); **H01L 23/66** (2006.01); **H01L 25/065** (2006.01)

CPC (source: EP US)  
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C-Set (source: EP US)  
1. **H01L 2924/351 + H01L 2924/00**  
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